

# PART NUMBER 75126D-ROCV

# Rochester Electronics Manufactured Components

Rochester branded components are manufactured using either die/wafers purchased from the original suppliers or Rochester wafers recreated from the original IP. All re-creations are done with the approval of the Original Component Manufacturer. (OCM)

Parts are tested using original factory test programs or Rochester developed test solutions to guarantee product meets or exceeds the OCM data sheet.

# **Quality Overview**

- ISO-9001
- AS9120 certification
- Qualified Manufacturers List (QML) MIL-PRF-38535
  - Class Q Military
  - Class V Space Level

Qualified Suppliers List of Distributors (QSLD)

 Rochester is a critical supplier to DLA and meets all industry and DLA standards.

Rochester Electronics, LLC is committed to supplying products that satisfy customer expectations for quality and are equal to those originally supplied by industry manufacturers.

The original manufacturer's datasheet accompanying this document reflects the performance and specifications of the Rochester manufactured version of this device. Rochester Electronics guarantees the performance of its semiconductor products to the original OCM specifications. 'Typical' values are for reference purposes only. Certain minimum or maximum ratings may be based on product characterization, design, simulation, or sample testing.



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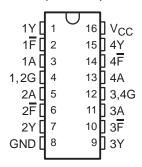
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- Meets or Exceeds the Requirements of IBM™ System 360/370 Input/Output Interface Specification GA22-6974-3
- Minimum Output Voltage of 3.11 V at  $I_{OH} = -59.3 \text{ mA}$
- Fault-Flag Circuit Output Signals Driver **Output Fault**
- Fault-Detection Current-Limit Circuit Minimizes Power Dissipation During a **Fault Condition**
- Dual Common Enable
- Individual Fault Flags
- Designed to Replace the MC3481

#### description

The SN75126 quadruple line driver is designed to meet the IBM 360/370 I/O specification A22-6974-3. The output voltage is 3.11 V minimum (at  $I_{OH} = -59.3$  mA) over the recommended ranges of supply voltage (4.5 V to 5.95 V) and temperature. Driver outputs use a fault-detection current-limit circuit to allow high drive current but still minimize power dissipation when the output is shorted to ground. The SN75126 is compatible with standard TTL logic and supply voltages.

#### D OR N PACKAGE (TOP VIEW)



#### **FUNCTION TABLE**

	INP	JTS	OUTPUTS				
	G	Α	Υ	F			
ſ	L	Χ	L	Н			
ı	Н	Н	Н	Н			
l	Н	Н	S	L			

H = high level,

L = low level,

X = irrelevant,

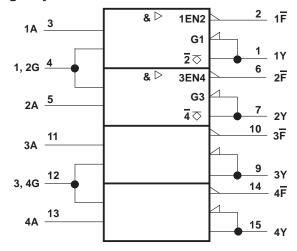
S = shorted to ground

Fault-flag circuitry is designed to sense and signal a line short on any Y line. Upon detecting an output fault condition, the fault-flag circuit forces the driver output into a low state and signals a fault condition by causing the fault-flag output to go low.

The SN75126 can drive a 50- $\Omega$  load or a 90- $\Omega$  load as used in many I/O systems. Optimum performance can be achieved when the device is used with either the SN75128 or SN75129 line receivers. Also, see the SN751730 for new 360/370 interface designs.

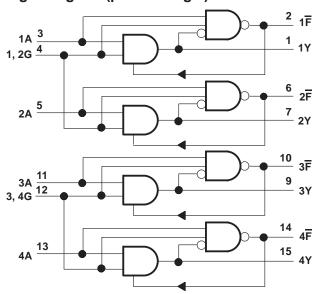
The SN75126 is characterized for operation from 0°C to 70°C.

#### logic symbol†

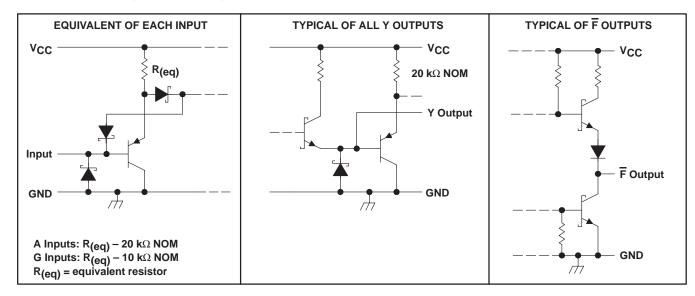


<sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

#### logic diagram (positive logic)



#### schematics of inputs and outputs



### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V <sub>CC</sub>	7 V
Input voltage, V <sub>I</sub>	7 V
Continuous total power dissipation	
Operating free-air temperature range, T <sub>A</sub>	0°C to 70°C
Storage temperature range, T <sub>stg</sub>	– 65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.



#### **DISSIPATION RATING TABLE**

PACKAGE	$T_{\mbox{A}} \leq 25^{\circ}\mbox{C}$ POWER RATING	DERATING FACTOR ABOVE T <sub>A</sub> = 25°C	T <sub>A</sub> = 70°C POWER RATING
D	950 mW	7.6 mW/°C	608 mW
N	1150 mW	9.2 mW/°C	736 mW

# recommended operating conditions

	MIN	NOM	MAX	UNIT
Supply voltage, V <sub>CC</sub>	4.5	5	5.95	V
High-level input voltage, V <sub>IH</sub>	2			V
Low-level input voltage, V <sub>IL</sub>			0.8	V
High-level output current, IOH			-59.3	mA
Operating free-air temperature, TA	0		70	°C

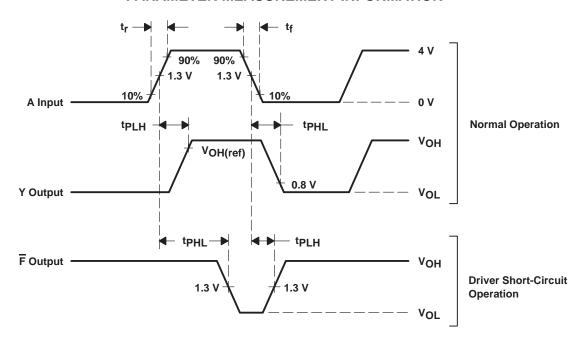
# electrical characteristics over recommended operating free-air temperature range

	PARAMETER			TEST CONDITION	IS	MIN	MAX	UNIT
VIK	Input clamp voltage	A,G	V <sub>CC</sub> = 4.5 V,	I <sub>I</sub> = -18 mA			-1.5	V
		Υ	$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -59.3 \text{ mA},$	V <sub>IH</sub> = 2 V	3.11		
Vон	High-level output voltage	Υ	$V_{CC} = 5.25 \text{ V},$	$I_{OH} = -41 \text{ mA},$	V <sub>IH</sub> = 2 V	3.9		V
		F	$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -400  \mu A$	V <sub>IH</sub> = 2 V	2.5		
		Υ	$V_{CC} = 5.5 \text{ V},$	$I_{OL} = -240 \mu A$ ,	V <sub>IL</sub> = 0.8 V		0.15	
VOL	Low-level output voltage	Υ	$V_{CC} = 5.95 \text{ V},$	$I_{OL} = -1 \text{ mA},$	V <sub>IL</sub> = 0.8 V		0.15	V
VOL	Low level output voltage	F	V <sub>CC</sub> = 4.5 V, V <sub>IH</sub> = 2 V	$I_{OL} = 8 \text{ mA},$	Y at 0 V,		0.5	<b>'</b>
1	Off state output current	Υ	$V_{CC} = 4.5 \text{ V},$	V <sub>I</sub> = 0,	V <sub>O</sub> = 3.11 V		100	μА
IO(off)	Off-state output current	Υ	$V_{CC} = 0$ ,	V <sub>I</sub> = 0,	V <sub>O</sub> = 3.11 V		200	μΑ
1.	Input current	Α	V <sub>CC</sub> = 4.5 V,	V <sub>I</sub> = 5.5 V			100	μΑ
1		G	VCC = 4.5 V,	V  = 5.5 V			200	μΑ
ΊΗ	High-level input current	Α	V00 = 45 V	$V_{CC} = 4.5 \text{ V}, \qquad V_{I} = 2.7 \text{ V}$			20	μΑ
חוי	Thigh level input current	G	VCC = 4.5 V, V = 2.7 V					
Ι <sub>Ι</sub> L	Low-level input current	Α	V <sub>CC</sub> = 5.95 V,	V <sub>I</sub> = 0.4 V			-250	-250 -500 μA
'IL	Low lover input ourient	G	VCC = 0.00 V,	V  = 0.4 V				μιν
		Υ	$V_{CC} = 5.5 \text{ V},$	$V_0 = 0$ ,	V <sub>IH</sub> = 2.7 V		-5	
los	Short-circuit output current	F	$V_{CC} = 5.5 \text{ V},$	V <sub>O</sub> = 0		-15	-100	mA
108	Chort circuit output current	Υ	$V_{CC} = 5.95 \text{ V},$	$V_O = 0$ ,	$V_{IH} = 2.7 V$		-5	l IIIA
		F	$V_{CC} = 5.95 \text{ V},$	VO = 0		-15	-110	
locu	Supply current, all outputs high		$V_{CC} = 5.5 \text{ V},$	No load,	V <sub>IH</sub> = 2 V		70	mA
Іссн	Supply current, an outputs high		$V_{CC} = 5.95 \text{ V},$	No load,	V <sub>IH</sub> = 2 V		80	
loci	Supply current, Y outputs low		$V_{CC} = 5.5 \text{ V},$	No load,	V <sub>IL</sub> = 0.8 V		55	mA
ICCL			$V_{CC} = 5.95 \text{ V},$	No load,	$V_{IL} = 0.8 V$		70	IIIA

## switching characteristics at $T_A = 25^{\circ}C$

PARAMETER		FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	MAX	UNIT
tPLH	Propagation delay time, low- to high-level output			$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$ $R_{L} = 50 \Omega,$		40	ns
tPHL	Propagation delay time, high- to low-level output	A	Y	$C_{L} = 50 \text{ pF},$		37	ns
t <u>PLH</u> tPHL	Ratio of propagation delay times			V <sub>OH(ref)</sub> = 3.11 V, See Figures 1 and 2	0.3	3	
tPLH	Propagation delay time, low- to high-level output	А	Y	$V_{CC} = 5.25 \text{ V to } 5.95 \text{ V},$ $R_L = 90 \Omega,$ $C_L = 50 \text{ pF},$		45	ns
tPHL	Propagation delay time, high- to low-level output			VOH(ref) = 3.9 V, See Figures 1 and 2		45	ns
tPLH	Propagation delay time, low- to high-level output	А	F	V <sub>CC</sub> = 5 V, C <sub>L</sub> = 15 pF,		60	ns
tPHL	Propagation delay time, high- to low-level output			$R_L = 2 k\Omega$ , See Figures 1 and 2		100	ns

#### PARAMETER MEASUREMENT INFORMATION

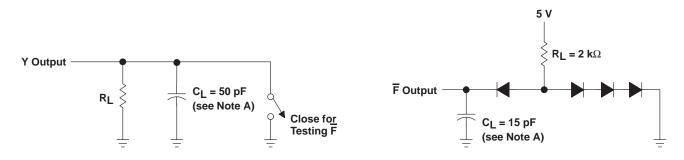


NOTE: The input pulse is supplied by a generator having the following characteristics: PRR  $\leq$  1 MHz, duty cycle  $\leq$  50%,  $t_f \leq$  6 ns,  $t_f \leq$  7 ns,  $t_f \leq$  8 ns,  $t_f \leq$  8 ns,  $t_f \leq$  9 ns,  $t_f$ 

Figure 1. Input and Output Voltage Waveforms



#### PARAMETER MEASUREMENT INFORMATION



NOTE A:  $C_L$  includes probe and stray capacitance.

Figure 2. Switching Characteristics Load Circuits



#### PACKAGE OPTION ADDENDUM

30-Mar-2005

#### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN75126N	OBSOLETE	PDIP	N	16	TBD	Call TI	Call TI

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND**: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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# N (R-PDIP-T\*\*)

## PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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